INTEGRATED CIRCUITS

DATA SHEET

83C508/87C508 CMOS single-chip 8-bit microcontroller

Preliminary specification

1995 May 15

IC20 Data Handbook

Philips Semiconductors



PHILIPS

83C508/87C508

DESCRIPTION

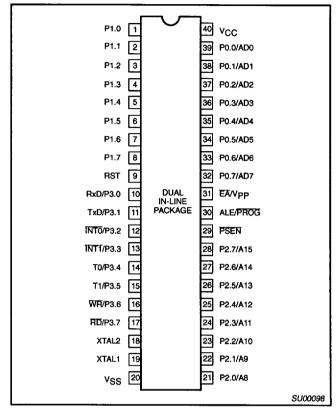
The 83C508 and 87C508 (hereafter referred to as 8XC508) Single-Chip 8-Bit Microcontroller is manufactured in an advanced CMOS process and is a derivative of the 80C51 microcontroller family. The 8XC508 has the same instruction set as the 80C51.

This device provides architectural enhancements that make it applicable in a variety of applications for general control systems. The 8XC508 contains $32k \times 8$ EPROM memory, the 83C508 contains $32k \times 8$ ROM memory, a volatile 256×8 read/write data memory, four 8-bit I/O ports, two 16-bit timer/event counters, a multi-source, two-priority-level, nested interrupt structure, a 24-by-16 bit unsigned divide, an enhanced UART and on-chip oscillator and timing circuits. For systems that require extra capability, the 8XC508 can be expanded using standard TTL compatible memories and logic.

FEATURES

- 80C51 central processing unit
- 32k × 8 EPROM expandable externally to 64k bytes
 - Quick Pulse programming algorithm
 - Two level program security system
- 256 x 8 RAM, expandable externally to 64k bytes
- Two 16-bit timer/counters
- Four 8-bit I/O ports
- Full-duplex enhanced UART
 - Framing error detection
 - Automatic address recognition
- Power control modes
 - Idle mode
 - Power-down mode
- Once (On Circuit Emulation) Mode
- Five package styles
- OTP package available
- 24-by-16 bit divide
 - Requires 4 machine cycles
 - 24-bit quotient and 16-bit remainder
- 24-by-16 multiply
 - Requires 4 machine cycles

PIN CONFIGURATIONS



ORDERING INFORMATION

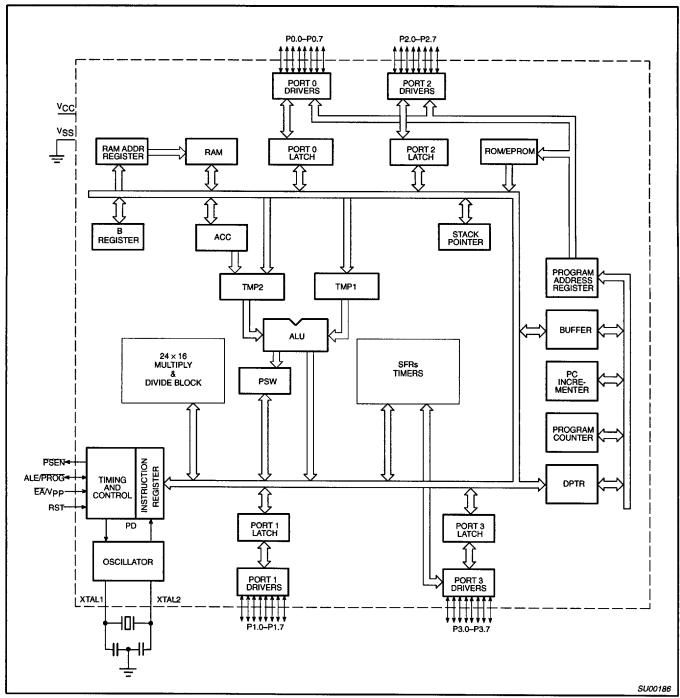
ROM	EPROM ¹		TEMPERATURE RANGE °C AND PACKAGE	FREQ. (MHz)	DRAWING NUMBER
P83C508IBP N	P87C508IBP N	OTP	0 to +70, 40-Pin Plastic Dual In-line Package	3.5 to 24	SOT129-1
	P87C508IBF FA	UV	0 to +70, 40-Pin Ceramic Dual In-line Package w/Window	3.5 to 24	0590B
P83C508IBA A	P87C508IBA A	ОТР	0 to +70, 44-Pin Plastic Leaded Chip Carrier	3.5 to 24	SOT187-2
	P87C508IBK KA	UV	0 to +70, 44-Pin Ceramic Leaded Chip Carrier w/Window	3.5 to 24	1472A
P83C508IBB BD	P87C508IBB BD	ОТР	0 to +70, 44-Pin Thin Quad Flat Pack	3.5 to 24	SOT389-1
P83C508NBP N	P87C508NBP N	ОТР	0 to +70, 40-Pin Plastic Dual In-Line Package	3.5 to 33	SOT129-1
	P87C508NBF FA	UV	0 to +70, 40-Pin Ceramic Dual In-line Package w/Window	3.5 to 33	0590B
P83C508NBA A	P87C508NBA A	OTP	0 to +70, 44-Pin Plastic Leaded Chip Carrier	3.5 to 33	SOT187-2
	P87C508NBL KA	UV .	0 to +70, 44-Pin Ceramic Leaded Chip Carrier w/Window	3.5 to 33	1472A
P83C508NBB BD	P87C508NBB BD	OTP	0 to +70, 44-Pin Thin Quad Flat Pack	3.5 to 33	SOT389-1

NOTE:

1. OTP = One Time Programmable EPROM. UV = Erasable EPROM.

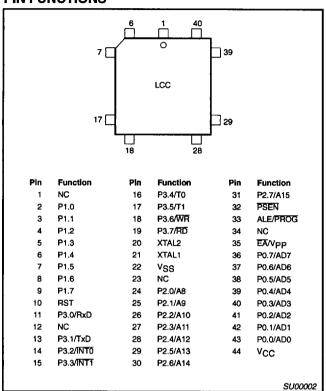
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BLOCK DIAGRAM

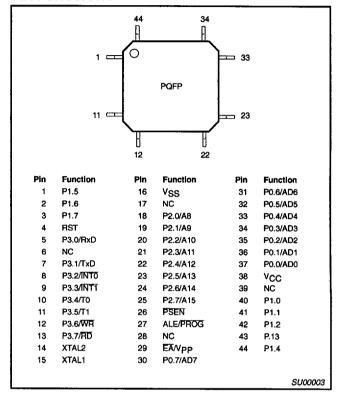


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CERAMIC AND PLASTIC LEADED CHIP CARRIER PIN FUNCTIONS



PLASTIC QUAD FLAT PACK PIN FUNCTIONS



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PIN DESCRIPTIONS

	PI	N NUMB	ER		
MNEMONIC	DIP	LCC	QFP	TYPE	NAME AND FUNCTION
V _{SS}	20	22	16	1	Ground: 0V reference.
V _{CC}	40	44	38	1	Power Supply: This is the power supply voltage for normal, idle, and power-down operation.
P0.0-0.7	39–32	43–36	37–30	I/O	Port 0: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pull-ups when emitting 1s. Port 0 also outputs the code bytes during program verification and receives code bytes during EPROM programming. External pull-ups are required during program verification.
P1.0-P1.7	1–8	2–9	40–44, 1–3	1/0	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups, except P1.6 and P1.7 which are open drain. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 1 pins that are externally pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I _{IL}). Port 1 also receives the low-order address byte during program memory verification.
P2.0-P2.7	21–28	24–31	18–25	I/O	Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 2 pins that are externally being pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I _{IL}). Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOV @Ri), port 2 emits the contents of the P2 special function register. Some Port 2 pins receive the high order address bits during EPROM programming and verification.
P3.0-P3.7	10–17	11, 13–19	5, 7–13	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: I _{IL}). Port 3 also serves the special features of the 80C51 family, as listed below:
	10	11	5	ı	RxD (P3.0): Serial input port
	11	13	7	0	TxD (P3.1): Serial output port
	12 13	14 15	8 9		INTO (P3.2): External interrupt INT1 (P3.3): External interrupt
	14	16	10	i	T0 (P3.4): Timer 0 external input
	15	17	11	l	T1 (P3.5): Timer 1 external input
	16	18	12	0	WR (P3.6): External data memory write strobe
	17	19	13	0	RD (P3.7): External data memory read strobe
RST	9	10	4	1	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V _{SS} permits a power-on reset using only an external capacitor to V _{CC} .
ALE/PROG	30	33	27	I/O	Address Latch Enable/Program Pulse: Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input (PROG) during EPROM programming.
PSEN	29	32	26	0	Program Store Enable: The read strobe to external program memory. When the 8XC508 is executing code from the external program memory, PSEN is activated twice each machine cycle, except that two PSEN activations are skipped during each access to external data memory. PSEN is not activated during fetches from internal program memory.
EA/V _{PP}	31	35	29	I	External Access Enable/Programming Supply Voltage: EA must be externally held low to enable the device to fetch code from external program memory locations 0000H and 3FFFH. If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 3FFFH. This pin also receives the 12.75V programming supply voltage (V _{PP}) during EPROM programming. If security bit 1 is programmed, EA will be internally latched on Reset.
XTAL1	19	21	15	ı	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	0	Crystal 2: Output from the inverting oscillator amplifier.

NOTE

To avoid "latch-up" effect at power-on, the voltage on any pin at any time must not be higher than V_{CC} + 0.5V or V_{SS} – 0.5V, respectively.

Table 1. 87C508 Special Function Registers

SYMBOL	DESCRIPTION	DIRECT ADDRESS	BIT A	ADDRESS	, SYMBOI	L, OR AL	TERNATIV	E PORT I	UNCTIO	N LSB	RESET VALUE
ACC*	Accumulator	E0H	E7	E6	E5	E4	E3	E2	E1	E0	00H
AUXR#	Auxiliary	8EH	-		-	_	_	_	_	AO	xxxxxxx0B
B*	B register	F0H	F7	F6	F5	F4	F3	F2	F1	F0	00Н
DPTR: DPH DPL	Data Pointer (2 bytes) Data Pointer High Data Pointer Low	83H 82H	FF	FE	FD	FC	FB	FA	F9	F8	00Н 00Н
DMCON	Divide/Multiply Control	F8H		T _	 	T _	DMMODE	AUTODM	DMSTRT	DMCTRL	00Н
DMB0 DMB1 DMB2 DMB3 DMB4 DMOP1	Divide/Multiply byte 0 Divide/Multiply byte 1 Divide/Multiply byte 2 Divide/Multiply byte 3 Divide/Multiply byte 4 Divide/Multiply operand 1 (LSB) Divide/Multiply oper-	91H 92H 93H 94H 96H 95H					- SMINOSE	Acresiii	DNOTH	BNOTHE	00H 00H 00H 00H 00H 00H
	and 2 (MSB)		AF	Α.	40	40	AD		40	40	
IE*	Interrupt Enable	A8H	EA	AE EC	AD ET2	AC ES	AB ET1	AA EX1	A9	A8 L EVA	
IE	interrupt Chable	АОП	BF	BE	BD	BC	BB	BA	ET0 B9	EX0 B8	00H
IP*	Interrupt Priority	B8H		PPC	PT2	PS	PT1	PX1	PT0	PX0	x0000000B
	interrupt i nonty	5011	87	86	85	84	83	82	81	80	X0000000B
P0*	Port 0	80H	AD7	AD6	AD5	AD4	AD3	AD2	AD1	ADO	FFH
			97	96	95	94	93	92	91	90	ł ''''
P1*	Port 1	90H	-	T -		T =		 -	-	-	FFH
			A7	A6	A5	A4	A3	A2	A1	A0	
P2*	Port 2	A0H	AD15	AD14	AD13	AD12	AD11	AD10	AD9	AD8	FFH
			B7	B6	B5	B4	B3	B2	B1	В0	1
P3*	Port 3	вон	RD	WR	T1	T0	INTT	INTO	TxD	RxD	FFH
				,			· · · · · · · · · · · · · · · · · · ·	· .]
PCON	Power Control	87H	SMOD1	SMOD0	<u> </u>	POF ¹	GF1	GF0	PD	IDL	00xxxx00B
DOWA	D 04-4 14/	Do.	D7	D6	D5	D4	D3	D2	D1	D0	
PSW*	Program Status Word	D0H	CY	AC	F0	RS1	RS0	ov	_	Р	00H
SADDR# SADEN#	Slave Address Slave Address Mask	A9H B9H									00H 00H
SBUF	Serial Data Buffer	99H									xxxxxxxxxB
		557.	9F	9E	9D	9C	9B	9A	99	98	***************************************
SCON*	Serial Control	98H	SMO	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SP	Stack Pointer	81H			_ 			1	L		07H
			8F	8E	8D	8C	8B	8A	89	88	1
TCON*	Timer Control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00Н
TH0	Timer High 0	8CH									00Н
TH1 TL0	Timer High 1 Timer Low 0	8DH 8AH									00H 00H
TL1	Timer Low 1	8BH	1								00H
TMOD	Timer Mode	89H	GATE	C/T	M1	MO	GATE	С/Т	M1	Mo	00Н
			C7	C6	C5	C4	C3	C2	C1	CO	1

SFRs are bit addressable.

[#] SFRs are modified from or added to the 80C51 SFRs.

^{1.} Reset value depends on reset source.

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ENHANCED UART

The 8XC508 UART has all of the capabilities of the standard 80C51 UART plus Framing Error Detection and Automatic Address Recognition. As in the 80C51, all four modes of operation are supported as well as the 9th bit in modes 2 and 3 that can be used to facilitate multiprocessor communication.

The Framing Error Detection allows the UART to look for missing stop bits. If a Stop bit is missing, the FE bit in the SCON SFR is set. The FE bit can be checked after each transmission to detect communication errors. The FE bit can only be cleared by software and is not affected by a valid stop bit.

Automatic Address Recognition is used to reduce the CPU service time for the serial port. The CPU only needs to service the UART when it is addressed and, with this done by the on-chip circuitry, the need for software overhead is greatly reduced. This mode works similar to the 9th bit communication mode, except that uses only 8 bits and the Stop bit is used to cause the RI bit to be set. There are two SFRs associated with this mode. They are SADDR, which holds the slave address and SADEN, which contains a mask that allows selective masking of the slave address so that broadcast addresses can be used.

HARDWARE MULTIPLY/DIVIDE UNIT

The 8XC508 contains a 24-by-16 bit hardware divide unit. The 24 bit dividend is stored in special function registers DMB2 – DMB0 and the divisors are in registers DMOP1 (LSB) and DMOP2 (MSB). A division operation returns the 24-bit result in registers DMB2 – DMB0 and a 16-bit remainder in register DMB3 (LSB) and DMB4 (MSB).

The divide unit provides two modes of operation, auto-start and flag-controlled. Auto-start mode is enabled by setting the AUTODM (auto divide/multiply) bit in the DMCON (divide/multiply control) register. If auto-start mode is enabled, writing to the divisor (DMOP1) will automatically start a division operation and will set the DMCTRL (divide/multiply control) and DMSTRT bits in the DMCON register. DMCTRL will automatically be cleared by the divide hardware when the division operation has been completed.

Flag controlled operation is initiated by setting the DMCTRL bit in the DMCON register which will start the division operation and also set the DMSTRT bit. The DMCTRL bit will automatically be cleared by the divide hardware when the division operation has been completed. DMSTRT can only be cleared by software.

The hardware divide unit of the 87C508 can also be used to perform a 24-by-16 bit multiply operation. Multiplication operation is selected by the DMMODE bit in the DMCON register (1 = multiply, 0 = divide). The 24-bit multiplicand is stored in the DMB2 – DMB0 registers. The multiplier is stored in the DMOP1 (LSB) and DMOP2 (MSB) registers. The 40 bit result of the multiply operation is stored in the DMB4 – DMB0 registers. Like division, the multiplication can be automatically started or software started. Autostart mode is enabled by setting the AUTODM bit in the DMCON register. Writing a multiplier to the DMOP1 register will automatically start a multiplication operation and will set the DMCTRL and DMSTRT bits in the DMCON register. DMCTRL will automatically be cleared by the multiply hardware when the multiplication operation is complete.

Flag controlled operation is initiated by setting the DMCTRL bit in the DMCON register, which will start the multiplication operation and also set the DMSTRT bit. The DMCTRL bit will automatically be cleared by the multiply hardware when the multiplication operation has been completed. DMSTRT can only be cleared by software.

POWER OFF FLAG

The Power Off Flag (POF) is set by on-chip circuitry when the V_{CC} level on the 8XC508 rises from 0 to 5V. The POF bit can be set or cleared by software allowing a user to determine if the reset is the result of a power-on or a warm start after powerdown. The V_{CC} level must remain above 3V for the POF to remain unaffected by the V_{CC} level.

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

Reset

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-on reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles. At power-on, the voltage on V_{CC} and RST must come up at the same time for a proper start-up.

Idle Mode

In the idle mode, the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

Power-Down Mode

To save even more power, a Power Down mode can be invoked by software. In this mode, the oscillator is stopped and the instruction that invoked Power Down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power Down mode is terminated.

On the 8XC508 either a hardware reset or external interrupt can use an exit from Power Down. Reset redefines all the SFRs but does not change the on-chip RAM. An external interrupt allows both the SFRs and the on-chip RAM to retain their values.

To properly terminate Power Down the reset or external interrupt should not be executed before $V_{\rm CC}$ is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize (normally less than 10ms).

With an external interrupt, INT0 and INT1 must be enabled and configured as level-sensitive. Holding the pin low restarts the oscillator but bringing the pin back high completes the exit. Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put the device into Power Down.

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Design Consideration

• When the idle mode is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal rest algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

ONCE™ Mode

The ONCE ("On-Circuit Emulation") Mode facilitates testing and debugging of systems using the 8XC508 without the 8XC508 having to be removed from the circuit. The ONCE Mode is invoked by:

- 1. Pull ALE low while the device is in reset and PSEN is high;
- 2. Hold ALE low as RST is deactivated.

While the device is in ONCE Mode, the Port 0 pins go into a float state, and the other port pins and ALE and PSEN are weakly pulled high. The oscillator circuit remains active. While the 8XC508 is in this mode, an emulator or test CPU can be used to drive the circuit. Normal operation is restored when a normal reset is applied.

Table 2. External Pin Status During Idle and Power-Down Mode

MODE	PROGRAM MEMORY	ALE	PSEN	PORT 0	PORT 1	PORT 2	PORT 3
ldle	Internal	1	1	Data	Data	Data	Data
ldle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

ABSOLUTE MAXIMUM RATINGS 1, 2, 3

PARAMETER	RATING	UNIT	
Operating temperature under bias	0 to +70	°C	
Storage temperature range	-65 to +150	°C	
Voltage on EA/V _{PP} pin to V _{SS}	0 to +13.0	V	
Voltage on any other pin to V _{SS}	-0.5 to +6.5	V	
Maximum I _{OL} per I/O pin	15	mA	
Power dissipation (based on package heat transfer limitations, not device power consumption)	1.5	w	

NOTES:

This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.

 Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.

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DC ELECTRICAL CHARACTERISTICS

 $T_{amb} = 0$ °C to +70°C, $V_{CC} = 5V \pm 10$ %, $V_{SS} = 0V$

		TEST		LIMITS		
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP ¹	MAX	UNIT
V _{IL}	Input low voltage, except EA		-0.5		0.2V _{CC} -0.1	٧
V _{IL1}	Input low voltage to EA		0		0.2V _{CC} 0.3	٧
V _{IH}	Input high voltage		0.7V _{CC}		V _{CC} +0.5	٧
V _{OL}	Output low voltage, ports 1, 2, 38	$I_{OL} = 100 \mu A$ $I_{OL} = 1.6 m A^2$ $I_{OL} = 3.5 m A$			0.3 0.45 1.0	V V V
V _{OL1}	Output low voltage, port 0, ALE, PSEN ⁸	$I_{OL} = 200 \mu A$ $I_{OL} = 3.2 m A^2$ $I_{OL} = 7.0 m A$			0.3 0.45 1.0	V V V
V _{OH}	Output high voltage, ports 1, 2, 3, ALE, PSEN ³	l _{OH} = -60μΑ, l _{OH} = -30μΑ l _{OH} = -10μΑ	V _{CC} - 1.5 V _{CC} - 0.7 V _{CC} - 0.3			V V V
V _{OH1}	Output high voltage (port 0 in external bus mode), ALE ⁹ , PSEN ³	l _{OH} = -7.0mA, l _{OH} = -3.2mA l _{OH} = -200μA	V _{CC} - 1.5 V _{CC} - 0.7 V _{CC} - 0.3			V V V
I _{IL}	Logical 0 input current, ports 1, 2, 3	$V_{IN} = 0.45V$			-50	μA
I _{TL}	Logical 1-to-0 transition current, ports 1, 2, 3	See note 4			-650	μА
l _{Li}	Input leakage current, port 0	0.45 V _{IN} < V _{CC} - 0.3			±10	μА
lcc	Power supply current: Active mode @ 16MHz ⁵ Idle mode @ 16MHz Power-down mode	See note 6		15 3 10	32 5 50	mA mA μA
R _{RST}	Internal reset pull-down resistor		50		225	kΩ
C _{IO}	Pin capacitance ¹⁰ (except EA)				15	pF

- Typical ratings are not guaranteed. The values listed are at room temperature, 5V.
- Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the Vols of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. IOL can exceed these conditions provided that no single output sinks more than 5mA and no more than two outputs exceed the test conditions.
- Capacitive loading on ports 0 and 2 may cause the VOH on ALE and PSEN to momentarily fall below the 0.9VCC specification when the address bits are stabilizing.
- 4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when VIN is approximately 2V.
- I_{CCMAX} at other frequencies is given by: Active mode: I_{CCMAX} = 1.50 × FREQ + 8: Idle mode: I_{CCMAX} = 0.14 × FREQ +2.31, where FREQ is the external oscillator frequency in MHz. ICCMAX is given in mA. See Figure 8.
- See Figures 9 through 12 for I_{CC} test conditions.

 Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
- 8. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows: 15mA (*NOTE: This is 85°C specification.) Maximum IOL per port pin:

Maximum IOL per 8-bit port:

26mA

Maximum total I_{OL} for all outputs: 71mA

If IoL exceeds the test condition, Vol may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

- ALE is tested to V_{OH1}, except when ALE is off then V_{OH} is the voltage specification.
- 10. Pin capacitance is less than 25pF. Pin capacitance of ceramic package is less than 15pF (except EA is 25pF).

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AC ELECTRICAL CHARACTERISTICS

 $T_{amb} = 0$ °C to +70°C or -40°C to +85°C, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V^{1, 2, 3}$

			16MHz	CLOCK	VARIABL	E CLOCK	
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	MAX	UNIT
1/t _{CLCL}	1	Oscillator frequency Speed versions : E			3.5	16	MHz
t _{LHLL}	1	ALE pulse width	85		2t _{CLCL} -40		ns
t _{AVLL}	1	Address valid to ALE low	22		t _{CLCL} -40		ns
tLLAX	1	Address hold after ALE low	32		t _{CLCL} -30		ns
tLLIV	1	ALE low to valid instruction in		150		4t _{CLCL} -100	ns
tLLPL	1	ALE low to PSEN low	32		t _{CLCL} -30		ns
t _{PLPH}	1	PSEN pulse width	142		3t _{CLCL} -45		ns
t _{PLIV}	1	PSEN low to valid instruction in		82		3t _{CLCL} -105	ns
t _{PXIX}	1	Input instruction hold after PSEN	0		0		ns
t _{PXIZ}	1	Input instruction float after PSEN		17	- · · · · · · · · · · · · · · · · · · ·	t _{CLCL} -25	ns
t _{AVIV}	1	Address to valid instruction in		207		5t _{CLCL} -105	ns
t _{PLAZ}	1	PSEN low to address float	<u> </u>	10		10	ns
Data Memo	ry			·			·
t _{RLRH}	2, 3	RD pulse width	275		6t _{CLCL} -100		ns
twLWH	2, 3	WR pulse width	275		6t _{CLCL} -100		ns
t _{RLDV}	2, 3	RD low to valid data in		147		5t _{CLCL} -165	ns
t _{RHDX}	2, 3	Data hold after RD	0		0		ns
t _{RHDZ}	2, 3	Data float after RD		65		2t _{CLCL} -60	ns
tLLDV	2, 3	ALE low to valid data in		350		8t _{CLCL} -150	ns
t _{AVDV}	2, 3	Address to valid data in		397		9t _{CLCL} -165	ns
tLLWL	2, 3	ALE low to RD or WR low	137	255	3t _{CLCL} -50	3t _{CLCL} +67	ns
t _{AVWL}	2, 3	Address valid to WR low or RD low	175		4t _{CLCL} -75		ns
tavwx	2, 3	Data valid to WR transition	42		t _{CLCL} -20		ns
twhax	2, 3	Data hold after WR	42		t _{CLCL} -20		ns
t _{QVWH}	3	Data valid to WR high	287		7t _{CLCL} -150		nş
t _{RLAZ}	2, 3	RD low to address float		0		0	ns
t _{WHLH}	2, 3	RD or WR high to ALE high	43	87	t _{CLCL} -20	t _{CLCL} +25	ns
External C	ock			<u> </u>			
tснсх	5	High time	20		20	tclcl-tclcx	ns
tclcx	5	Low time	20		20	tclcl-tclcx	ns
tсьсн	5	Rise time		5		5	ns
tchcL	5	Fall time		5		5	ns
Shift Regis	ter			·			1
txlxl	4	Serial port clock cycle time	750		12t _{CLCL}		ns
tavхн	4	Output data setup to clock rising edge	492		10t _{CLCL} -133		ns
txHQX	4	Output data hold after clock rising edge	8		2t _{CLCL} -117		ns
t _{XHDX}	4	Input data hold after clock rising edge	0		0		ns
t _{XHDV}	4	Clock rising edge to input data valid		492		10t _{CLCL} -133	ns

Parameters are valid over operating temperature range unless otherwise specified.
 Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
 Interfacing the 87C54 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.

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AC ELECTRICAL CHARACTERISTICS

Tamb = 0°C to +70°C or -40°C to +85°C, V_{CC} = 5V ±10%, V_{SS} = 0V^{1, 2, 3}

			24MHz	CLOCK	VARIABLI	E CLOCK ⁴	
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	MAX	TINU
1/t _{CLCL}	1	Oscillator frequency Speed versions: I			3.5	24	MHz
t _{LHLL}	1	ALE pulse width	43		2t _{CLCL} -40		ns
t _{AVLL}	1	Address valid to ALE low	17		t _{CLCL} -25		ns
t _{LLAX}	1	Address hold after ALE low	17		t _{CLCL} -25		ns
t _{LLIV}	1	ALE low to valid instruction in		150	, . <u></u>	4t _{CLCL} -65	ns
t _{LLPL}	1	ALE low to PSEN low	17		t _{CLCL} -25		ns
t _{PLPH}	1	PSEN pulse width	80		3t _{CLCL} -45		ns
t _{PLIV}	1	PSEN low to valid instruction in		65		3t _{CLCL} -60	ns
t _{PXIX}	1	Input instruction hold after PSEN	0		0		ns
t _{PXIZ}	1	Input instruction float after PSEN		37		t _{CLCL} -25	ns
t _{AVIV}	1	Address to valid instruction in		128		5t _{CLCL} -80	ns
t _{PLAZ}	1	PSEN low to address float		10		10	ns
Data Memo	ry			· · · · · · · · · · · · · · · · · · ·			
t _{RLRH}	2, 3	RD pulse width	150		6t _{CLCL} -100		ns
twLWH	2, 3	WR pulse width	150		6t _{CLCL} -100		ns
t _{RLDV}	2, 3	RD low to valid data in		118		5t _{CLCL} -90	ns
t _{RHDX}	2, 3	Data hold after RD	0		0		ns
t _{RHDZ}	2, 3	Data float after RD		55		2t _{CLCL} -28	ns
t _{LLDV}	2, 3	ALE low to valid data in		183		8t _{CLCL} -150	ns
t _{AVDV}	2, 3	Address to valid data in		210		9t _{CLCL} -165	ns
t _{LLWL}	2, 3	ALE low to RD or WR low	75	175	3t _{CLCL} -50	3t _{CLCL} +50	ns
t _{AVWL}	2, 3	Address valid to WR low or RD low	92		4t _{CLCL} -75	0202	ns
tavwx	2, 3	Data valid to WR transition	12		t _{CLCL} -30		ns
twhqx	2, 3	Data hold after WR	17		t _{CLCL} -25	·- ·	ns
t _{QVWH}	3	Data valid to WR high	162		7t _{CLCL} -130	·	ns
t _{RLAZ}	2, 3	RD low to address float		0	0202	0	ns
twHLH	2, 3	RD or WR high to ALE high	17	67	t _{CLCL} -25	t _{CLCL} +25	ns
External C	lock				OLOL	1 0202	
tchcx	5	High time	17		17	tclcl-tclcx	ns
tCLCX	5	Low time	17	 	17	tclcl-tclcx	ns
t _{CLCH}	5	Rise time		5		5	ns
tCHCL	5	Fall time		5		5	ns
Shift Regis	<u> </u>					L	1
t _{XLXL}	4	Serial port clock cycle time	505		12t _{CLCL}	I	ns
t _{QVXH}	4	Output data setup to clock rising edge	283		10t _{CLCL} -133		ns
txHQX	4	Output data hold after clock rising edge	3	 	2t _{CLCL} -80		ns
t _{XHDX}	4	Input data hold after clock rising edge	0	 	0		ns
t _{XHDV}	4	Clock rising edge to input data valid		283		10t _{CLCL} -133	ns

Parameters are valid over operating temperature range unless otherwise specified.
 Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
 Interfacing the 87C54 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
 Variable clock is specified for oscillator frequencies greater than 16MHz to 24MHz. For frequencies equal or less than 16MHz, see 16MHz "AC Electrial Characteristics", page 10.

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AC ELECTRICAL CHARACTERISTICS T_{amb} = 0°C to+70°C or -40°C to +85°C; V_{CC} = 5V ±10%, V_{SS} = 0V^{1, 2, 3}

			33MHz	CLOCK	VARIABL	E CLOCK	
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	MAX	UNIT
1/t _{CLCL}	1	Oscillator frequency Speed version : N			3.5	33	MHz
^t LHLL	1	ALE pulse width	20		2t _{CLCL} -40		ns
t _{AVLL}	1	Address valid to ALE low	5		t _{CLCL} -25		ns
t _{LLAX}	1	Address hold after ALE low	5		t _{CLCL} -25		ns
t _{LLIV}	1	ALE low to valid instruction in		55		4t _{CLCL} -65	ns
^t LLPL	1	ALE low to PSEN low	5		t _{CLCL} -25		ns
t _{PLPH}	1	PSEN pulse width	45		3t _{CLCL} -45		ns
t _{PLIV}	1	PSEN low to valid instruction in		30		3t _{CLCL} -60	ns
t _{PXIX}	1	Input instruction hold after PSEN	0		0		ns
t _{PXIZ}	1	Input instruction float after PSEN		5		t _{CLCL} -25	ns
t _{AVIV}	1	Address to valid instruction in		70		5t _{CLCL} -80	ns
t _{PLAZ}	1	PSEN low to address float		10		10	ns
Data Memo	ory						•
t _{RLRH}	2, 3	RD pulse width	80		6t _{CLCL} -100		ns
twLWH	2, 3	WR pulse width	80		6t _{CLCL} -100		ns
t _{RLDV}	2, 3	RD low to valid data in		60		5t _{CLCL} -90	ns
t _{RHDX}	2, 3	Data hold after RD	0		0		ns
t _{RHDZ}	2, 3	Data float after RD		32	,	2t _{CLCL} -28	ns
t _{LLDV}	2, 3	ALE low to valid data in		90		8t _{CLCL} -150	ns
t _{AVDV}	2, 3	Address to valid data in		105		9t _{CLCL} -165	ns
t _{LLWL}	2, 3	ALE low to RD or WR low	40	140	3t _{CLCL} -50	3t _{CLCL} +50	ns
t _{AVWL}	2, 3	Address valid to WR low or RD low	45		4t _{CLCL} -75	0202	ns
t _{QVWX}	2, 3	Data valid to WR transition	0		t _{CLCL} -30		ns
twhox	2, 3	Data hold after WR	5		t _{CLCL} -25		ns
t _{QVWH}	3	Data valid to WR high	82		7t _{CLCL} -130		ns
t _{RLAZ}	2, 3	RD low to address float		0	9202	0	ns
twhLH	2, 3	RD or WR high to ALE high	5	55	t _{CLCL} -25	t _{CLCL} +25	ns
External C	lock					1 0202	
tchcx	5	High time	10		10	t _{CLCL} - t _{CLCX}	ns
tCLCX	5	Low time	10		10	tolor tolox	ns
t _{CLCH}	5	Rise time		5		5	ns
t _{CHCL}	5	Fall time		5		5	ns
Shift Regis	ter			1			
t _{XLXL}	4	Serial port clock cycle time	363		12t _{CLCL}		ns
t _{QVXH}	4	Output data setup to clock rising edge	167	1	10t _{CLCL} -133		ns
txHQX	4	Output data hold after clock rising edge	0		2t _{CLCL} -60		ns
t _{XHDX}	4	Input data hold after clock rising edge	0		0		ns
txHDV	4	Clock rising edge to input data valid		167		10t _{CLCL} -133	ns

NOTES:

Parameters are valid over operating temperature range unless otherwise specified.
 Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
 Interfacing the 8XC508 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0

83C508/87C508

AC ELECTRICAL CHARACTERISTICS

			24MHz	CLOCK	VARIABL	E CLOCK	
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	MAX	דואט
1/t _{CLCL}	1	Oscillator frequency Speed versions : G : I			3.5 3.5	20 24	MHz
t _{LHLL}	1	ALE pulse width	43		2t _{CLCL} -40		ns
t _{AVLL}	1	Address valid to ALE low	17		t _{CLCL} -25	-	ns
t _{LLAX}	1	Address hold after ALE low	17		t _{CLCL} -25		ns
t _{LLIV}	1	ALE low to valid instruction in		102	Ü	4t _{CLCL}	ns
t _{LLPL}	1	ALE low to PSEN low	17		t _{CLCL} -25		ns
t _{PLPH}	1	PSEN pulse width	80		3t _{CLCL} -45		ns
t _{PLIV}	1	PSEN low to valid instruction in		65		3t _{CLCL} -60	ns
t _{PXIX}	1	Input instruction hold after PSEN	0		0		ns
t _{PXIZ}	1	Input instruction float after PSEN		17		t _{CLCL} -25	ns
t _{AVIV}	1	Address to valid instruction in		128		5t _{CLCL} -80	ns
t _{PLAZ}	1	PSEN low to address float	j	10		10	ns
Data Memo	ry		•	· · · · · · · ·			
t _{RLRH}	2, 3	RD pulse width	150		6t _{CLCL} -100		ns
twwH	2, 3	WR pulse width	150		6t _{CLCL} -100		ns
t _{RLDV}	2, 3	RD low to valid data in		118		5t _{CLCL} -90	ns
t _{RHDX}	2, 3	Data hold after RD	0		0		ns
t _{RHDZ}	2, 3	Data float after RD		55		2t _{CLCL} -28	ns
tLLDV	2, 3	ALE low to valid data in		180		8t _{CLCL} -150	ns
tavdv	2, 3	Address to valid data in		210		9t _{CLCL} -165	ns
tLLWL	2, 3	ALE low to RD or WR low	75	175	3t _{CLCL} -50	3t _{CLCL} +50	ns
t _{AVWL}	2, 3	Address valid to WR low or RD low	92		4t _{CLCL} -75		ns
tavwx	2, 3	Data valid to WR transition	12		t _{CLCL} -30		ns
twhqx	2, 3	Data hold after WR	17		t _{CLCL} -25		ns
t _{QVWH}	3	Data valid to WR high	142		7t _{CLCL} -150		ns
t _{RLAZ}	2, 3	RD low to address float		0		0	ns
twhLH	2, 3	RD or WR high to ALE high	17	67	t _{CLCL} -25	t _{CLCL} +25	ns
External C	ock		•	·			
tchcx	5	High time	12		20	1	ns
tclcx	5	Low time	12		20		ns
t _{CLCH}	5	Rise time		20		20	ns
t _{CHCL}	5	Fall time		20		20	ns
Shift Regis	ter		-	1			
t _{XLXL}	4	Serial port clock cycle time	1		12t _{CLCL}		μѕ
t _{QVXH}	4	Output data setup to clock rising edge	492		10t _{CLCL} -133		ns
txHQX	4	Output data hold after clock rising edge	23		2t _{CLCL} -60		ns
t _{XHDX}	4	Input data hold after clock rising edge	0		0		ns
txHDV	4	Clock rising edge to input data valid		283		10t _{CLCL} -133	ns

NOTES:

Parameters are valid over operating temperature range unless otherwise specified.
 Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
 Interfacing the 8XC508 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.

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EXPLANATION OF THE AC SYMBOLS

Each timing symbol has five characters. The first character is always 't' (= time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designations are:

- A Address
- C Clock
- D Input data
- H Logic level high
- I Instruction (program memory contents)
- L Logic level low, or ALE

- P PSEN
- Q Output data
- R RD signal
- t Time
- V Valid
- W- WR signal
- X No longer a valid logic level
- Z Float

Examples: t_{AVLL} = Time for address valid to ALE low. t_{LLPL} =Time for ALE low to PSEN low.

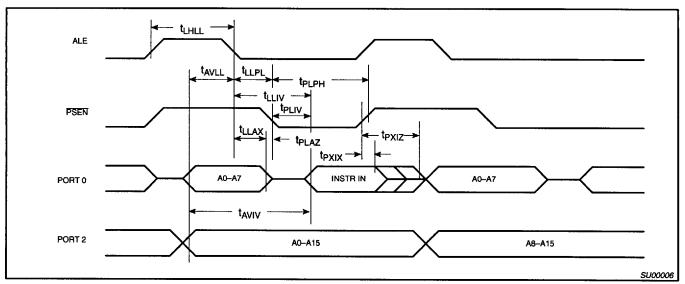


Figure 1. External Program Memory Read Cycle

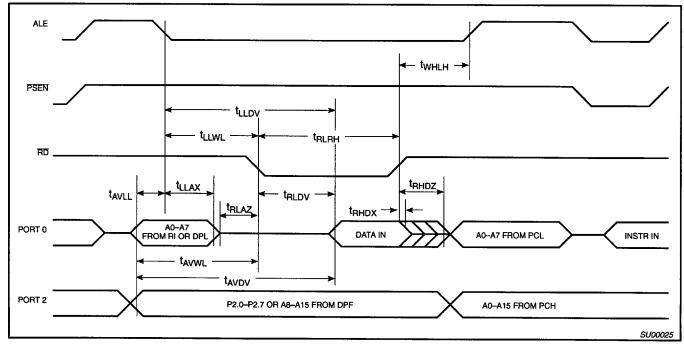


Figure 2. External Data Memory Read Cycle

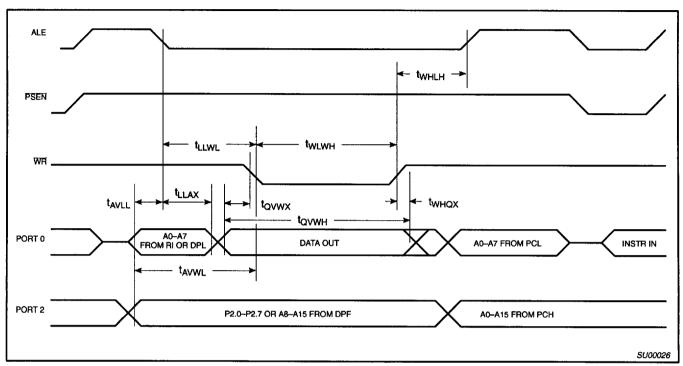


Figure 3. External Data Memory Write Cycle

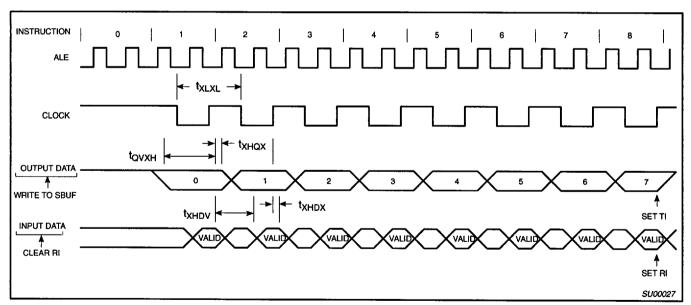


Figure 4. Shift Register Mode Timing

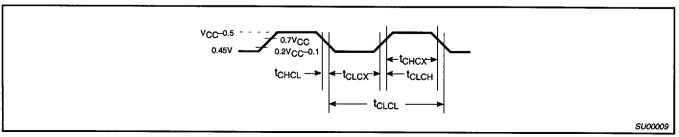


Figure 5. External Clock Drive

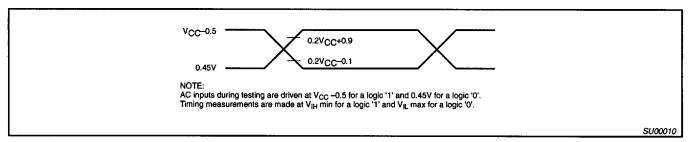


Figure 6. AC Testing Input/Output

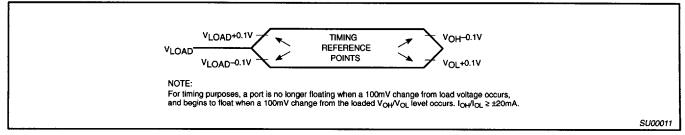


Figure 7. Float Waveform

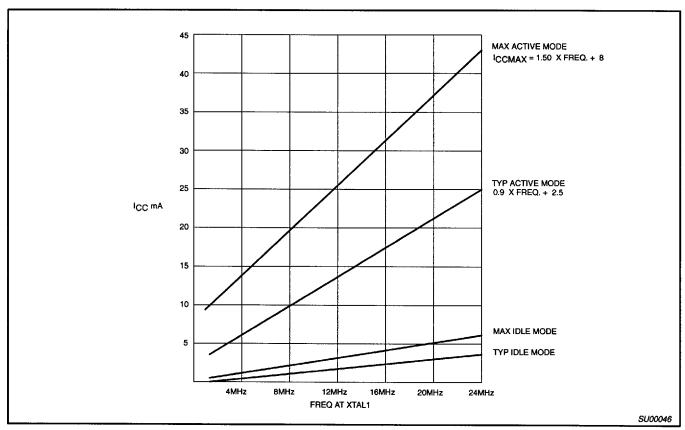


Figure 8. I_{CC} vs. FREQ Valid only within frequency specifications of the device under test

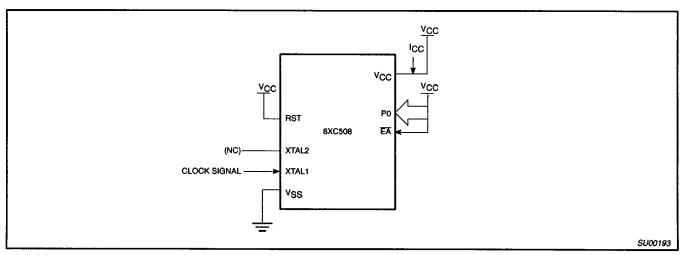


Figure 9. I_{CC} Test Condition, Active Mode All other pins are disconnected

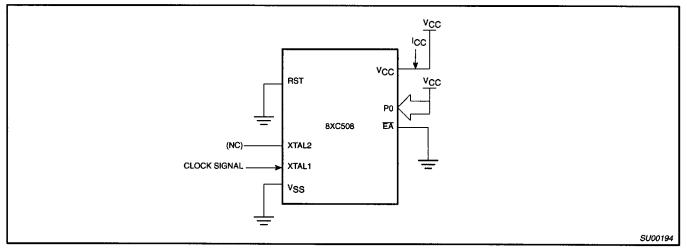


Figure 10. I_{CC} Test Condition, Idle Mode All other pins are disconnected

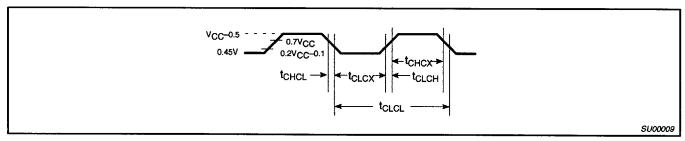


Figure 11. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes $t_{CLCH} = t_{CHCL} = 5$ ns

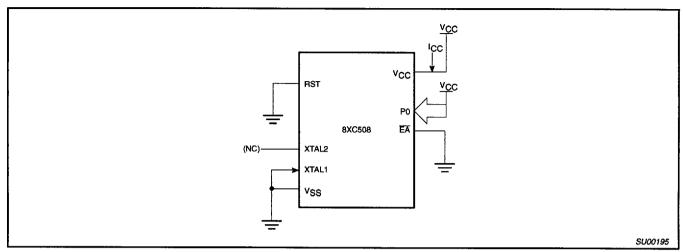


Figure 12. I_{CC} Test Condition, Power Down Mode All other pins are disconnected. V_{CC} = 2V to 5.5V

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EPROM CHARACTERISTICS

The 87C508 is programmed by using a modified Quick-Pulse Programming™ algorithm. It differs from older methods in the value used for V_{PP} (programming supply voltage) and in the width and number of the ALE/PROG pulses.

The 87C508 contains two signature bytes that can be read and used by an EPROM programming system to identify the device. The signature bytes identify the device as an 87C508 manufactured by Philips.

Table 3 shows the logic levels for reading the signature byte, and for programming the program memory, the encryption table, and the security bits. The circuit configuration and waveforms for quick-pulse programming are shown in Figures 13 and 14. Figure 15 shows the circuit configuration for normal program memory verification.

Quick-Pulse Programming

The setup for microcontroller quick-pulse programming is shown in Figure 13. Note that the 87C508 is running with a 4 to 6MHz oscillator. The reason the oscillator needs to be running is that the device is executing internal address and program data transfers.

The address of the EPROM location to be programmed is applied to ports 1 and 2, as shown in Figure 13. The code byte to be programmed into that location is applied to port 0. RST, PSEN and pins of ports 2 and 3 specified in Table 3 are held at the 'Program Code Data' levels indicated in Table 3. The ALE/PROG is pulsed low 25 times as shown in Figure 14.

To program the encryption table, repeat the 25 pulse programming sequence for addresses 0 through 1FH, using the 'Pgm Encryption Table' levels. Do not forget that after the encryption table is programmed, verification cycles will produce only encrypted data.

To program the security bits, repeat the 25 pulse programming sequence using the 'Pgm Security Bit' levels. After one security bit is programmed, further programming of the code memory and encryption table is disabled. However, the other security bit can still be programmed.

Note that the $\overline{\text{EA/V}_{PP}}$ pin must not be allowed to go above the maximum specified V_{PP} level for any amount of time. Even a narrow glitch above that voltage can cause permanent damage to the device. The V_{PP} source should be well regulated and free of glitches and overshoot.

Program Verification

If security bit 2 has not been programmed, the on-chip program memory can be read out for program verification. The address of the program memory locations to be read is applied to ports 1 and 2 as shown in Figure 15. The other pins are held at the 'Verify Code Data' levels indicated in Table 3. The contents of the address location will be emitted on port 0. External pull-ups are required on port 0 for this operation.

If the encryption table has been programmed, the data presented at port 0 will be the exclusive NOR of the program byte with one of the encryption bytes. The user will have to know the encryption table contents in order to correctly decode the verification data. The encryption table itself cannot be read out.

Reading the Signature Bytes

The signature bytes are read by the same procedure as a normal verification of locations 030H and 031H, except that P3.6 and P3.7 need to be pulled to a logic low. The values are:

(030H) = 15H indicates manufactured by Philips

(031H) = BDH indicates 87C508

Program/Verify Algorithms

Any algorithm in agreement with the conditions listed in Table 3, and which satisfies the timing specifications, is suitable.

Erasure Characteristics

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelengths shorter than approximately 4,000 angstroms. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room level fluorescent lighting) could cause inadvertent erasure. For this and secondary effects, it is recommended that an opaque label be placed over the window. For elevated temperature or environments where solvents are being used, apply Kapton tape Fluorglas part number 2345–5, or equivalent.

The recommended erasure procedure is exposure to ultraviolet light (at 2537 angstroms) to an integrated dose of at least 15W-s/cm². Exposing the EPROM to an ultraviolet lamp of $12,000\mu \text{W/cm}^2$ rating for 20 to 39 minutes, at a distance of about 1 inch, should be sufficient.

Erasure leaves the array in an all 1s state.

Table 3. EPROM Programming Modes

	9							
MODE	RST	PSEN	ALE/PROG	EA/V _{PP}	P2.7	P2.6	P3.7	P3.6
Read signature	1	0	1	1	0	0	0	0
Program code data	1	0	0*	V _{PP}	1	0	1	1
Verify code data	1	0	1	1	0	0	1	1
Pgm encryption table	1	0	0*	V _{PP}	1	0	1	0
Pgm security bit 1	1	0	0*	V _{PP}	1	1	1	1
Pgm security bit 2	1	0	0*	V_{PP}	1	1	0	0
Pgm security bit 3	1	0	0*	V _{PP}	0	1	0	1

NOTES:

- 1. '0' = Valid low for that pin, '1' = valid high for that pin.
- 2. $V_{PP} = 12.75V \pm 0.25V$.
- 3. V_{CC} = 5V±10% during programming and verification.
- ALE/PROG receives 25 programming pulses while V_{PP} is held at 12.75V. Each programming pulse is low for 100μs (±10μs) and high for a minimum of 10μs.

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[™]Trademark phrase of Intel Corporation.

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Table 4. Program Security Bits

PR	OGRAM L	оск віт	S ^{1, 2}	
	SB1	SB2	SB3	PROTECTION DESCRIPTION
1	U	U	U	No Program Security features enabled. (Code verify will still be encrypted by the Encryption Array if programmed.)
2	Р	υ	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, EA is sampled and latched on Reset, and further programming of the EPROM is disabled.
3	Р	Р	U	Same as 2, also verify is disabled.
4	P	Р	Р	Same as 3, external execution is disabled. Internal data RAM is not accessible.

NOTES:

- P programmed. U unprogrammed.
 Any other combination of the security bits is not defined.

ROM CODE SUBMISSION

When submitting ROM code for the 83C508, the following must be specified:

- 1. 32k byte user ROM data
- 2. 32 byte ROM encryption key
- 3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 3FFFH	DATA	7:0	User ROM Data
4000H to 401FH	KEY	7:0	ROM Encryption Key FFH = no encryption
4020H	SEC	0	ROM Security Bit 1
4020H	SEC	1	ROM Security Bit 2 0 = enable security 1 = disable security
4020H	SEC	3	ROM Security Bit 3 0 = enable security 1 = disable security

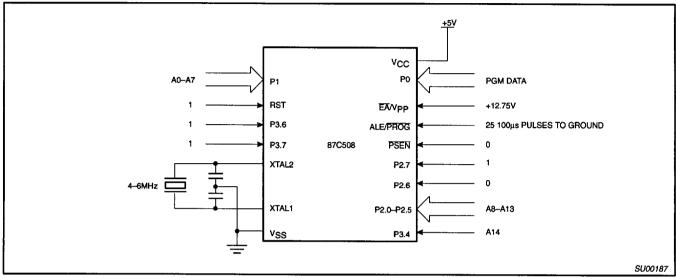


Figure 13. Programming Configuration

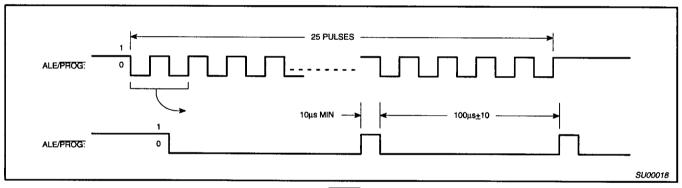


Figure 14. PROG Waveform

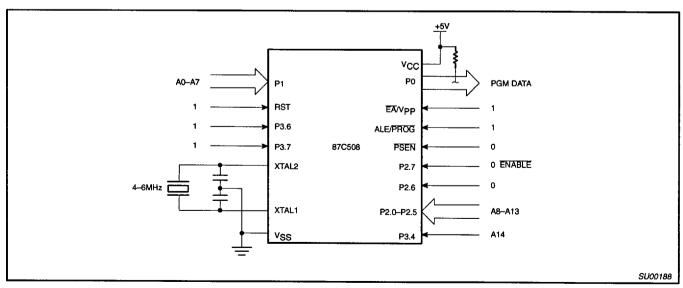


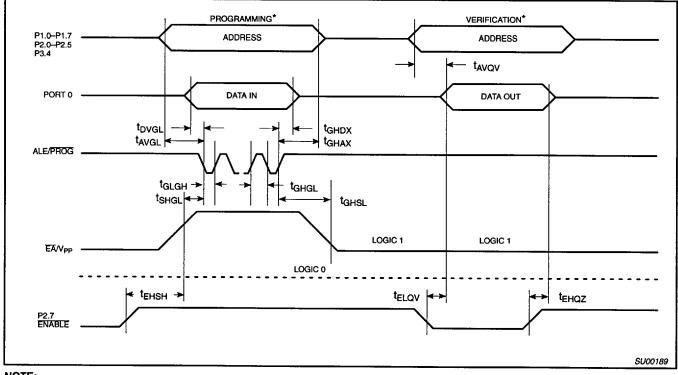
Figure 15. Program Verification

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EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS

 $T_{amb} = 21^{\circ}C$ to +27°C, $V_{CC} = 5V\pm10\%$, $V_{SS} = 0V$ (See Figure 16)

SYMBOL	PARAMETER	MIN	MAX	UNIT
V _{PP}	Programming supply voltage	12.5	13.0	V
I _{PP}	Programming supply current		50	mA
1/t _{CLCL}	Oscillator frequency	4	6	MHz
t _{AVGL}	Address setup to PROG low	48t _{CLCL}		
t _{GHAX}	Address hold after PROG	48t _{CLCL}		
t _{DVGL}	Data setup to PROG low	48t _{CLCL}		
t _{GHDX}	Data hold after PROG	48t _{CLCL}		
t _{EHSH}	P2.7 (ENABLE) high to V _{PP}	48t _{CLCL}		
t _{SHGL}	V _{PP} setup to PROG low	10		μs
t _{GHSL}	V _{PP} hold after PROG	10		μs
t _{GLGH}	PROG width	90	110	μs
t _{AVQV}	Address to data valid		48t _{CLCL}	
t _{ELQZ}	ENABLE low to data valid		48t _{CLCL}	
t _{EHQZ}	Data float after ENABLE	0	48t _{CLCL}	
^t GHGL	PROG high to PROG low	10		μs



NOTE:

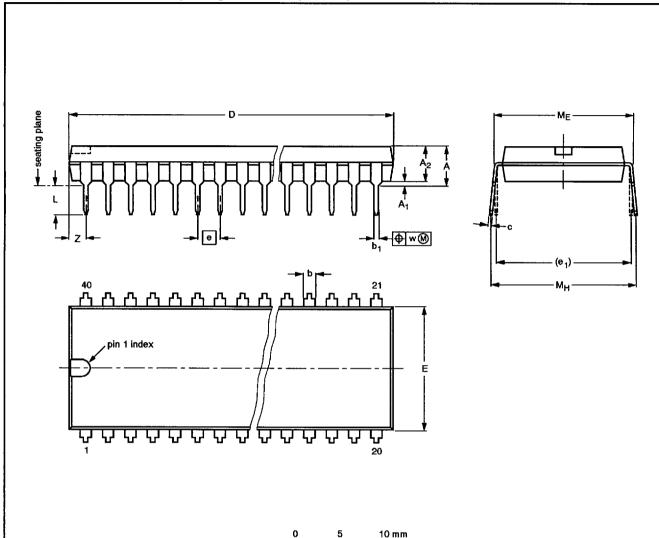
* FOR PROGRAMMING VERIFICATION SEE FIGURE 13. FOR VERIFICATION CONDITIONS SEE FIGURE 15.

Figure 16. EPROM Programming and Verification

83C508/87C508

DIP40: plastic dual in-line package; 40 leads (600 mil)

SOT129-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

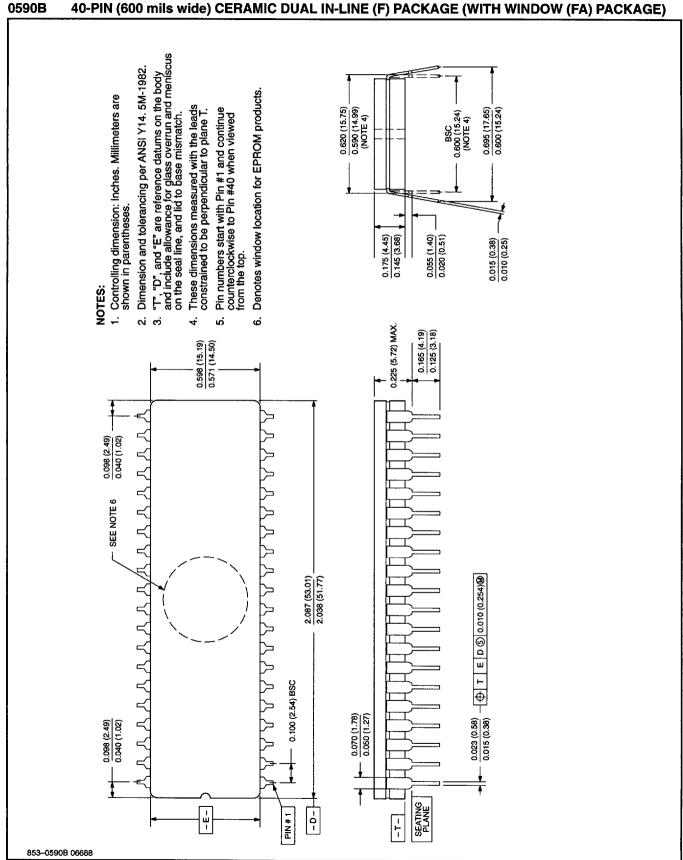
UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	ME	MH	w	Z ⁽¹⁾ max.
mm	4.7	0.51	4.0	1.70 1.14	0.53 0.38	0.36 0.23	52.50 51.50	14.1 13.7	2.54	15.24	3.60 3.05	15.80 15.24	17.42 15.90	0.254	2.25
inches	0.19	0.020	0.16	0.067 0.045	0.021 0.015	0.014 0.009	2.067 2.028	0.56 0.54	0.10	0.60	0.14 0.12	0.62 0.60	0.69 0.63	0.01	0.089

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

1	OUTLINE		REFER	EUROPEAN	100115 0 455		
L	VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
	SOT129-1	051G08	MO-015AJ				92-11-17- 95-01-14

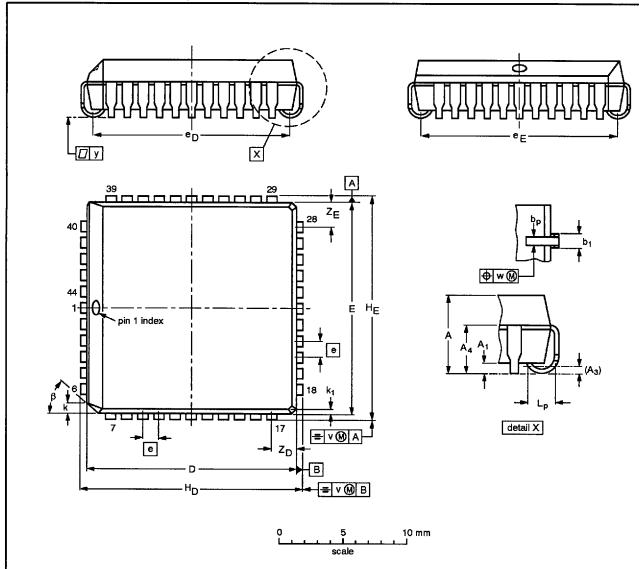
0590B



83C508/87C508

PLCC44: plastic leaded chip carrier; 44 leads

SOT187-2



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

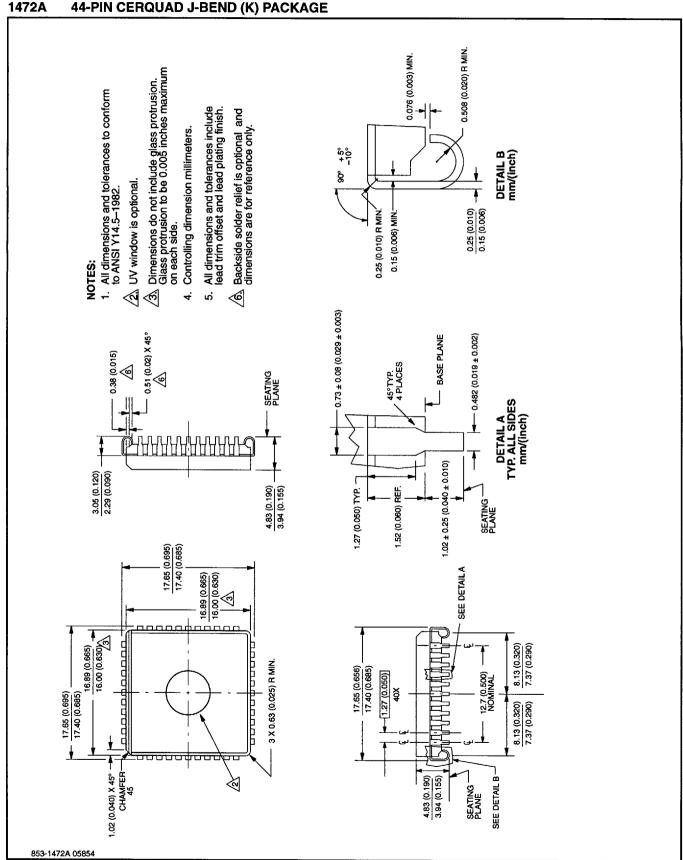
UNIT	Α	A ₁ min.	A ₃	A ₄ max.	Ьp	b ₁	D ⁽¹⁾	E ⁽¹⁾	e	e _D	еE	НD	HE	k	k ₁ max.	Lp	v	w	у	- 1	Z _E ⁽¹⁾ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0 53 0 33			16 66 16.51	1 27	16.00 14.99	16.00 14.99			1 22 1.07	0.51	1.44 1.02	0.18	0.18	0.10	2.16	2.16	0
inches	0.180 0.165	0.020	0.01	0 12		0.032 0.026			0.05	0.630 0.590	0.630 0.590	0.695 0.685	0.695 0.685	0.048 0.042	0.020	0.057 0.040	0.007	0.007	0.004	0.085	0.085	45°

Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

OUTLINE		REFERE	EUROPEAN	100115-0-175			
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE		
SOT187-2	112E10	MO-047AC		€	92-11-17 95-02-25		

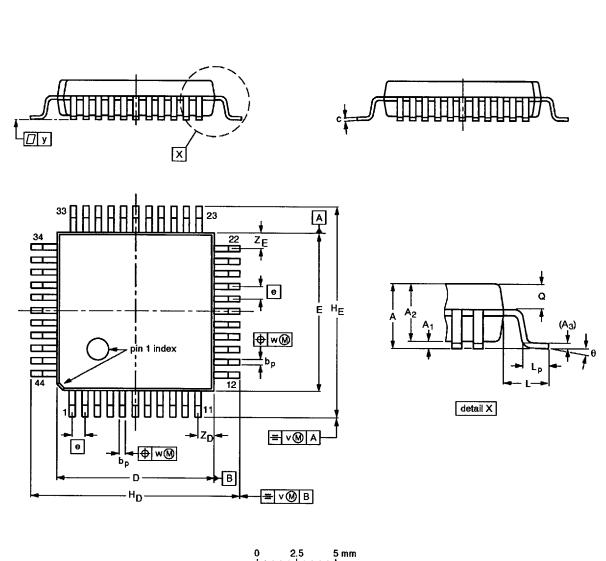
1472A 44-PIN CERQUAD J-BEND (K) PACKAGE



83C508/87C508

plastic low profile quad flat package; 44 leads; body 10 x 10 x 1.4 mm

SOT389-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	•	H _D	HE	L	Lp	Q	v	w	у	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.60	0.15 0.05	1.45 1.35	0.25	0.45 0.30	0.20 0.12	10.10 9.90	10.10 9.90	0.80	12.15 11.85			0.75 0.45		0.20	0.20	0.10	1.14 0.85	1.14 0.85	7° 0°

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT389-1						95-02-25